

400V N-Channel MOSFET

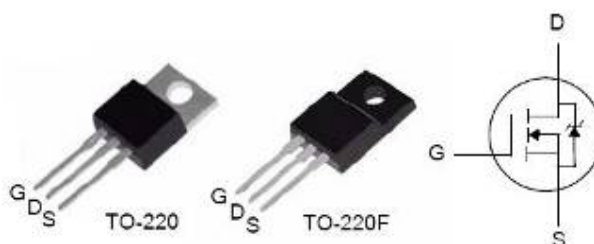
General Features

- Low ON Resistance
- Low Gate Charge (typical 34nC)
- Fast Switching
- 100% Avalanche Tested
- RoHS Compliant/Lead Free

Applications

- High Efficiency SMPS
- Adaptor/Charger
- LCD Panel Power
- Switching application

BV_{DSS}	$R_{DS(ON)}$ (Max.)	I_D
400V	0.50Ω	10A



Ordering Information

Part Number	Package	Marking
FTP10N40	TO-220	FTP10N40
FTA10N40	TO-220F	FTA10N40

Absolute Maximum Ratings

$T_C=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	FTP10N40	FTA10N40	Unit
V _{DSS}	Drain-to-Source Voltage ^[1]	400		V
I _D	Continuous Drain Current	10	10*	A
I _{D@100} °C	Continuous Drain Current	Figure 3		
I _{DM}	Pulsed Drain Current, V _{GS@10V} ^[2]	Figure 6		
P _D	Power Dissipation	125	31	W
	Derating Factor above 25°C	1.0	0.25	W/°C
V _{GS}	Gate-to-Source Voltage	±30		V
E _{AS}	Single Pulse Avalanche Energy L=7.2mH, I _D =10A	360		mJ
dv/dt	Peak Diode Recovery dv/dt ^[3]	4.5		V/ns
T _L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300		°C
T _J and T _{STG}	Operating and Storage Temperature Range	-55 to 150		

*Drain Current limited by Maximum Junction Temperature.

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	FTP06N40	FTA06N40	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.0	4.0	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	65	65	



FTP10N40/FTA10N40

Electrical Characteristics

OFF Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	400	--	--	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	--	0.6	--	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	--	--	12	μA	$V_{DS}=400V, V_{GS}=0V$
		--	--	100		$V_{DS}=320V, V_{GS}=0V$, $T_C=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Current	--	--	100	nA	$V_{GS}=+30V$
		--	--	-100		$V_{GS}=-30V$

ON Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	0.43	0.50	Ω	$V_{GS}=10V, I_D=6.0A^{[4]}$
$V_{GS(TH)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS} = V_{GS}, I_D=250\mu A$
gfs	Forward Transconductance	--	10.5	--	S	$V_{DS} = 15V, I_D=10A^{[4]}$

Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{ISS}	Input Capacitance	--	1138	--	pF	$V_{GS}=0V$ $V_{DS}=25V$ $f=1.0MHz$ Figure 14
C_{OSS}	Output Capacitance	--	119	--		
C_{RSS}	Reverse Transfer Capacitance	--	24	--		
Q_G	Total Gate Charge	--	34	--	nC	$V_{DD}=200V$ $I_D=10A$ Figure 15
Q_{GS}	Gate-to-Source Charge	--	3	--		
Q_{GD}	Gate-to-Drain (Miller) Charge	--	12.4	--		

Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{d(ON)}$	Turn-on Delay Time	--	31	--	ns	$V_{DD}=200V$ $I_D=10A$ $V_{GS}=10V$ $R_G=20\Omega$
t_{rise}	Rise Time	--	91	--		
$t_{d(OFF)}$	Turn-off Delay Time	--	44	--		
t_{fall}	Fall Time	--	55	--		

Source-Drain Diode Characteristics
 $T_c=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Units	Test Conditions
I_{SD}	Continuous Source Current (Body Diode)	--	--	10	A	Integral P-N diode in MOSFET
I_{SM}	Maximum Pulsed Current(Body Diode)	--	--	40	A	
V_{SD}	Diode Forward Voltage	--	--	1.2	V	$I_S=10\text{A}$, $V_{GS}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	247	--	ns	$V_{GS}=0\text{V}$ $I_F=10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$
Q_{rr}	Reverse Recovery Charge	--	1540	--	nC	

NOTE:

[1] $T_J=+25^{\circ}\text{C}$ to $+150^{\circ}\text{C}$

[2] Repetitive rating, pulse width limited by maximum junction temperature.

[3] $I_{SD}=10\text{A}$, $di/dt \leq 100\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, $T_J=+150^{\circ}\text{C}$

[4] Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.

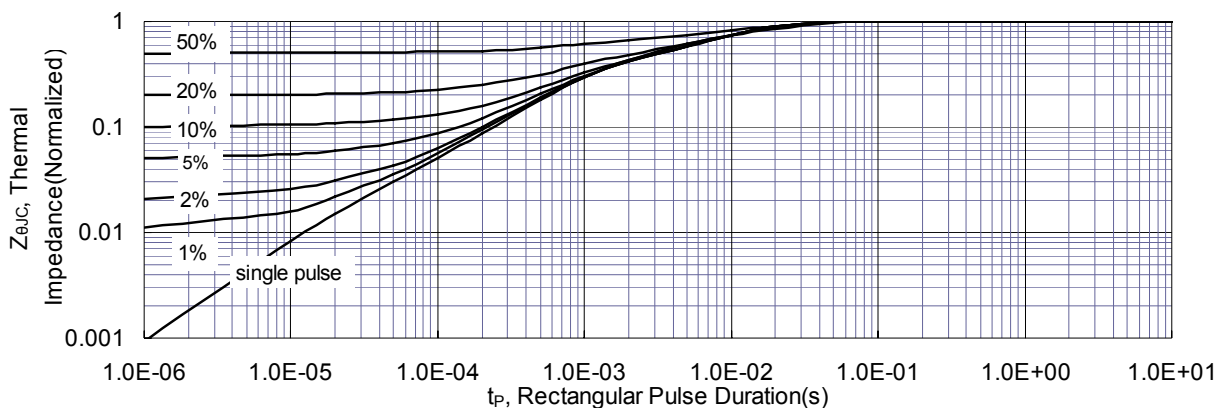
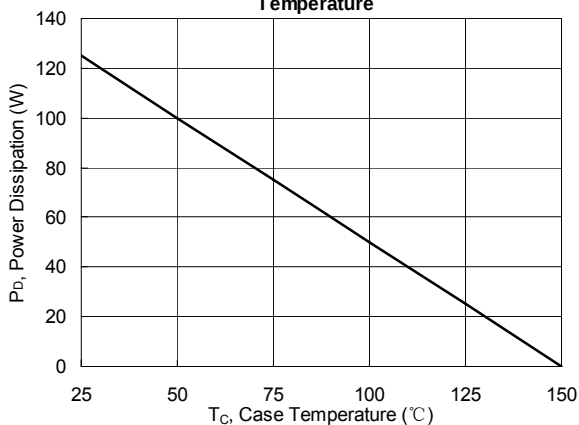
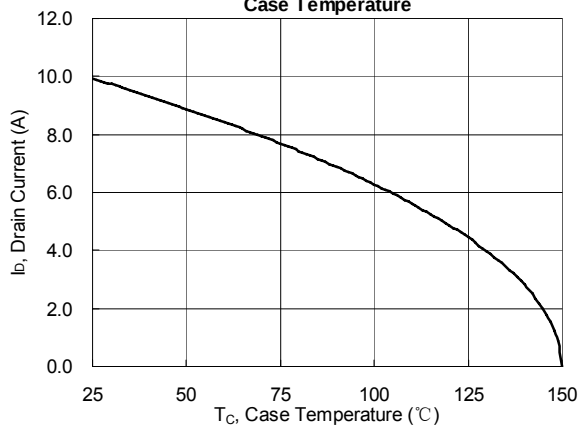
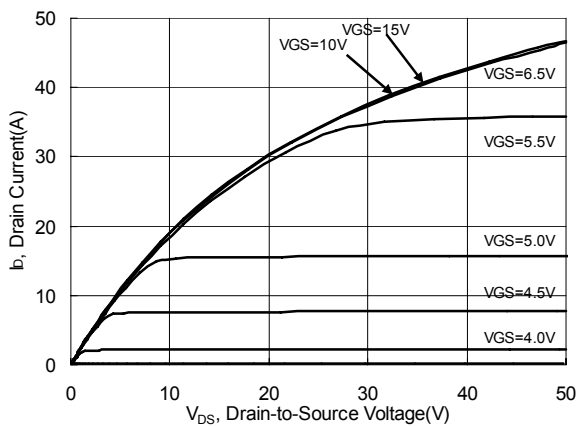
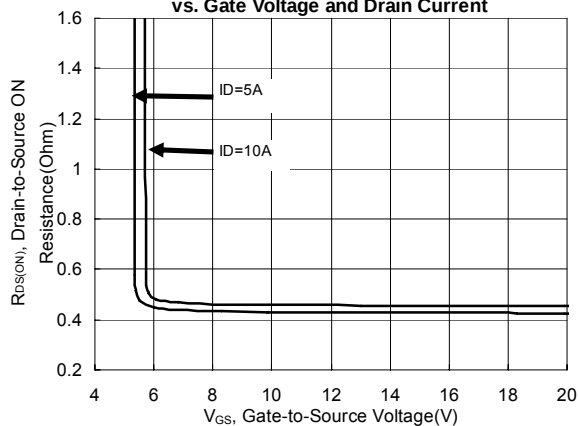
Figure 1. Maximum Effective Thermal Impedance, Junction-to-Case

Figure 2. Maximum Power Dissipation vs. Case Temperature

Figure 3. Maximum Continuous Drain Current vs Case Temperature

Figure 4. Typical Output Characteristics

Figure 5. Typical Drain-to-Source ON Resistance vs. Gate Voltage and Drain Current


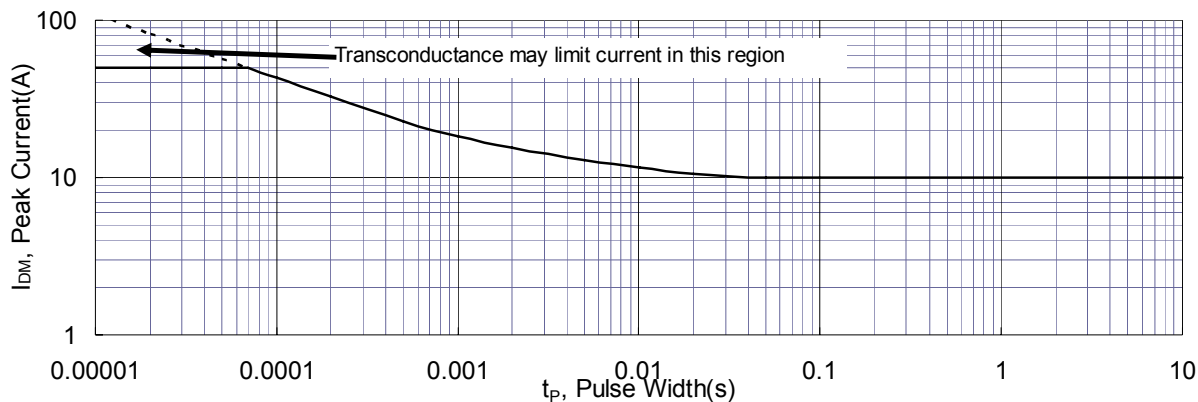
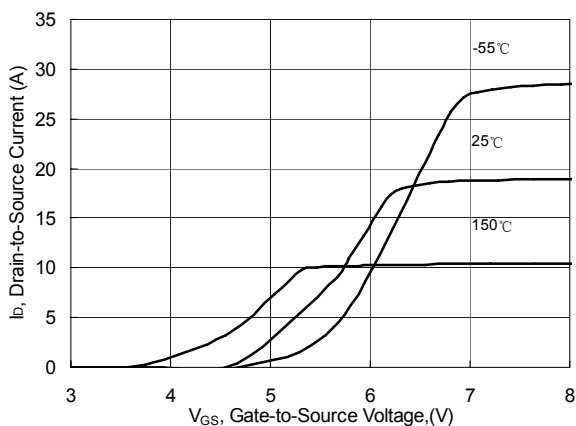
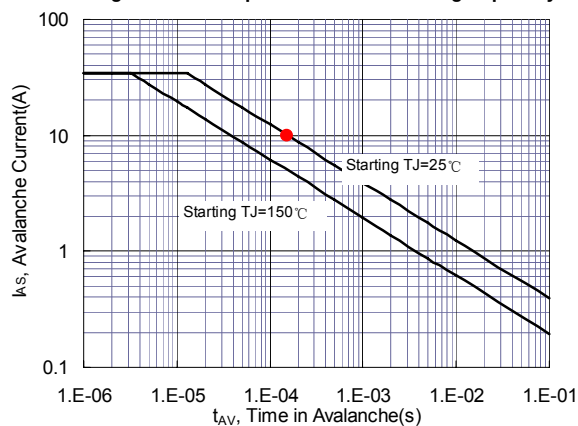
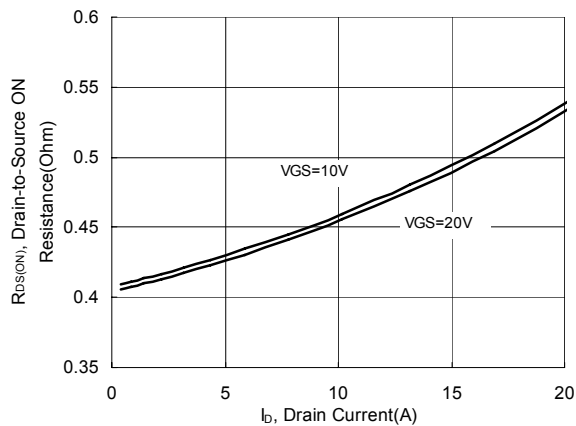
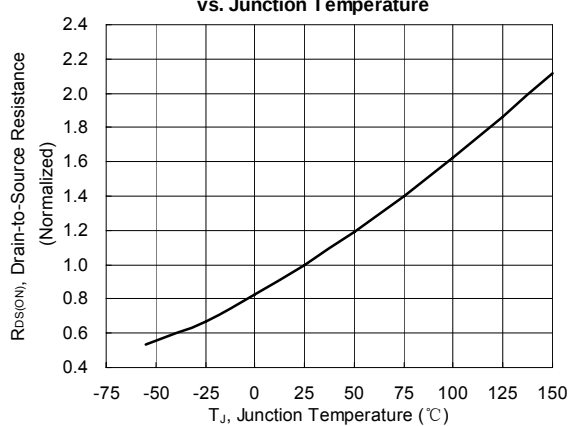
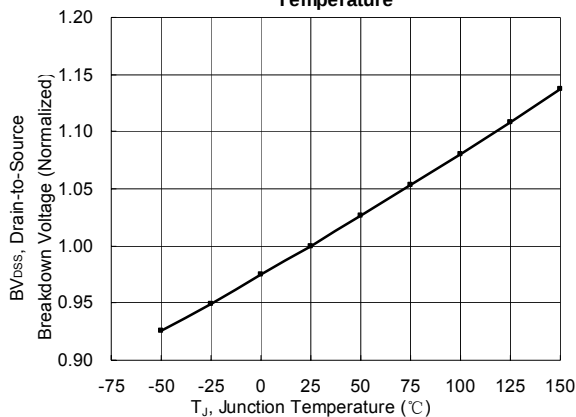
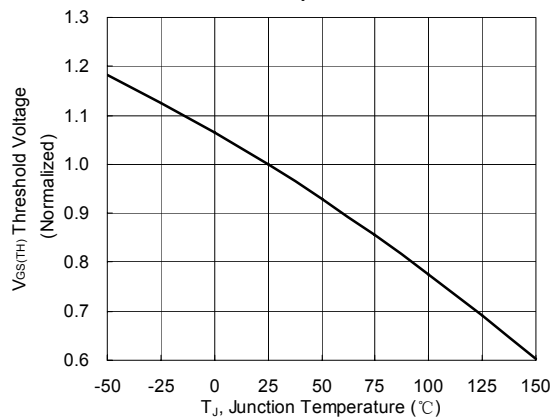
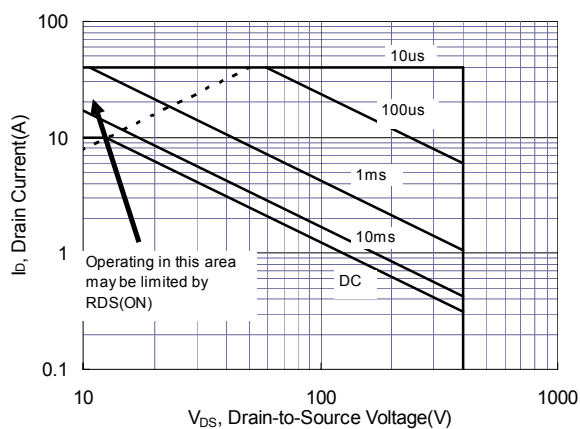
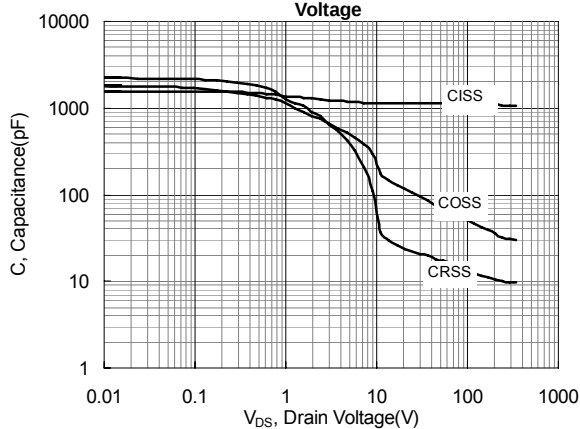
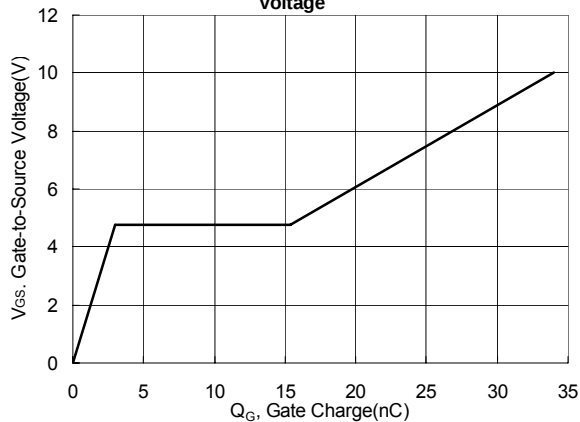
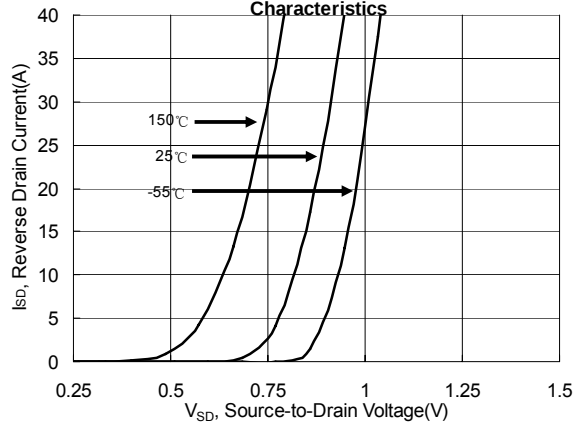
Figure 6. Maximum Peak Current Capability

Figure 7. Typical Transfer Characteristics

Figure 8. Unclamped Inductive Switching Capability

Figure 9. Typical Drain-to-Source ON Resistance

Figure 10. Typical Drain-to-Source On Resistance vs. Junction Temperature


Figure 11. Typical Breakdown Voltage vs. Junction Temperature

Figure 12. Typical Threshold Voltage vs. Junction Temperature

Figure 13. Maximum Forward Safe Operation Area

Figure 14. Typical Capacitance vs. Drain-to-Source Voltage

Figure 15. Typical Gate Charge vs. Gate-to-Source Voltage

Figure 16. Typical Body Diode Transfer Characteristics


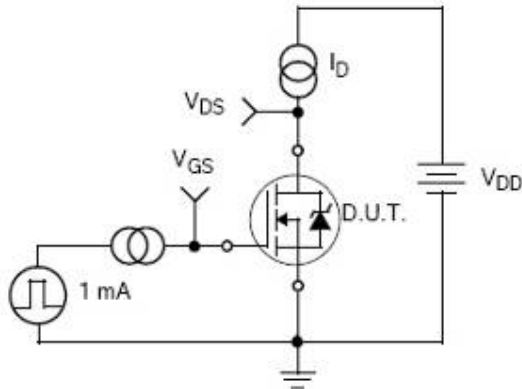
Test Circuit


Figure 17. Gate Charge Test Circuit

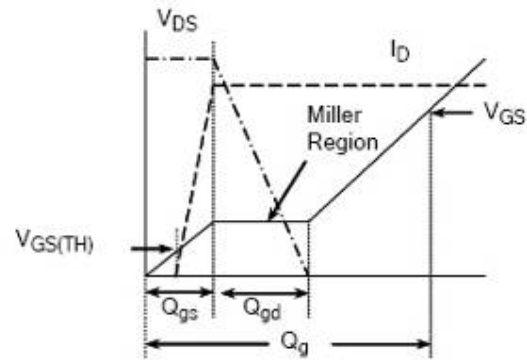


Figure 18. Gate Charge Waveform

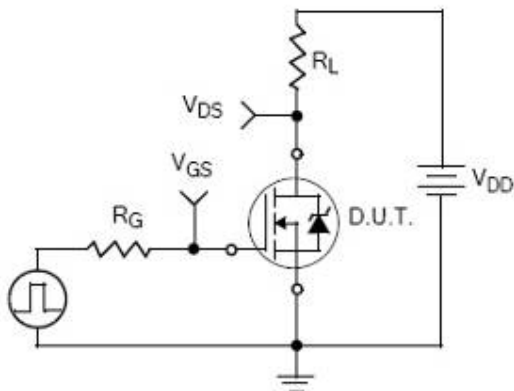


Figure 19. Resistive Switching Test Circuit

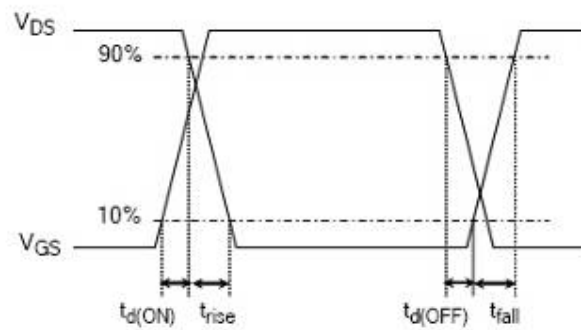


Figure 20. Resistive Switching Waveforms

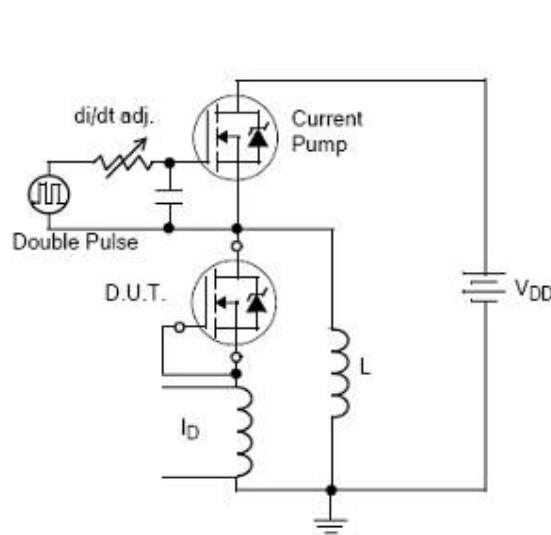


Figure 21. Diode Reverse Recovery Test Circuit

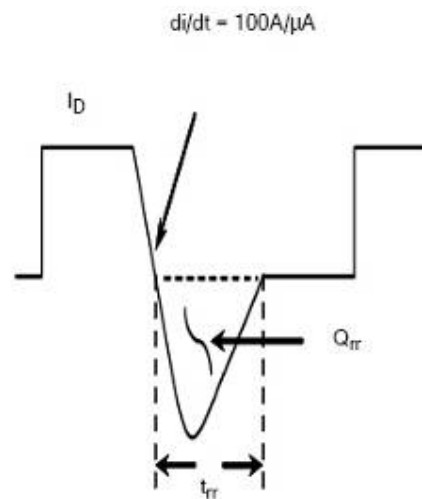


Figure 22. Diode Reverse Recovery Waveform

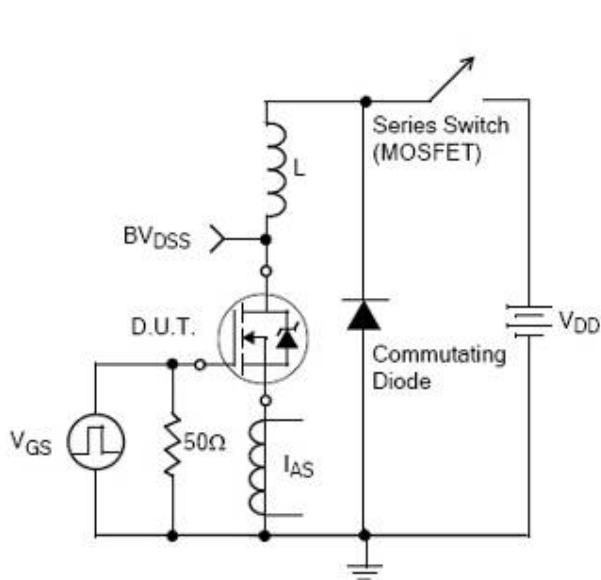


Figure 23. Unclamped Inductive Switching Test Circuit

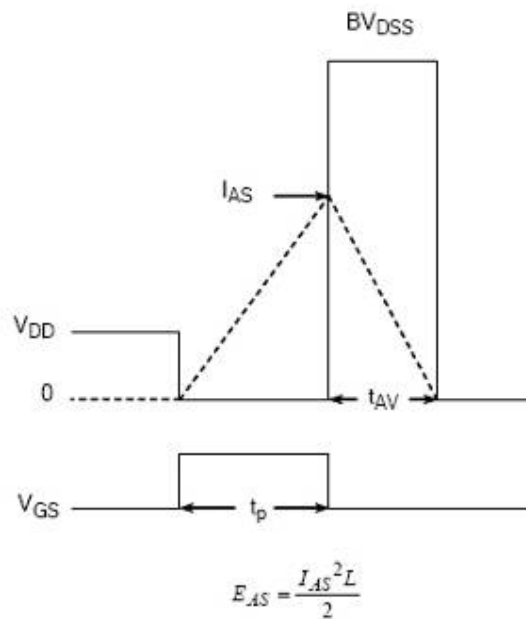
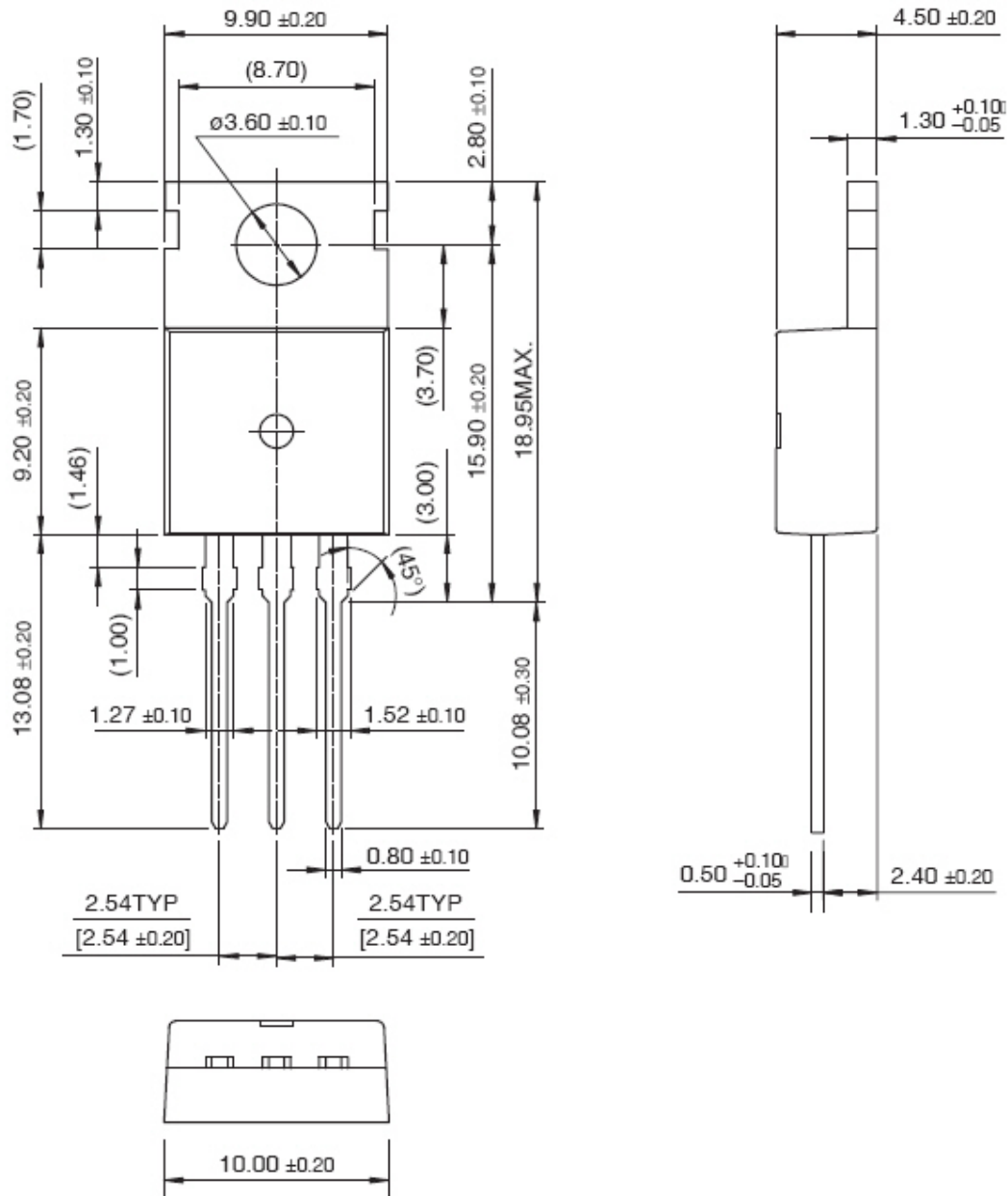
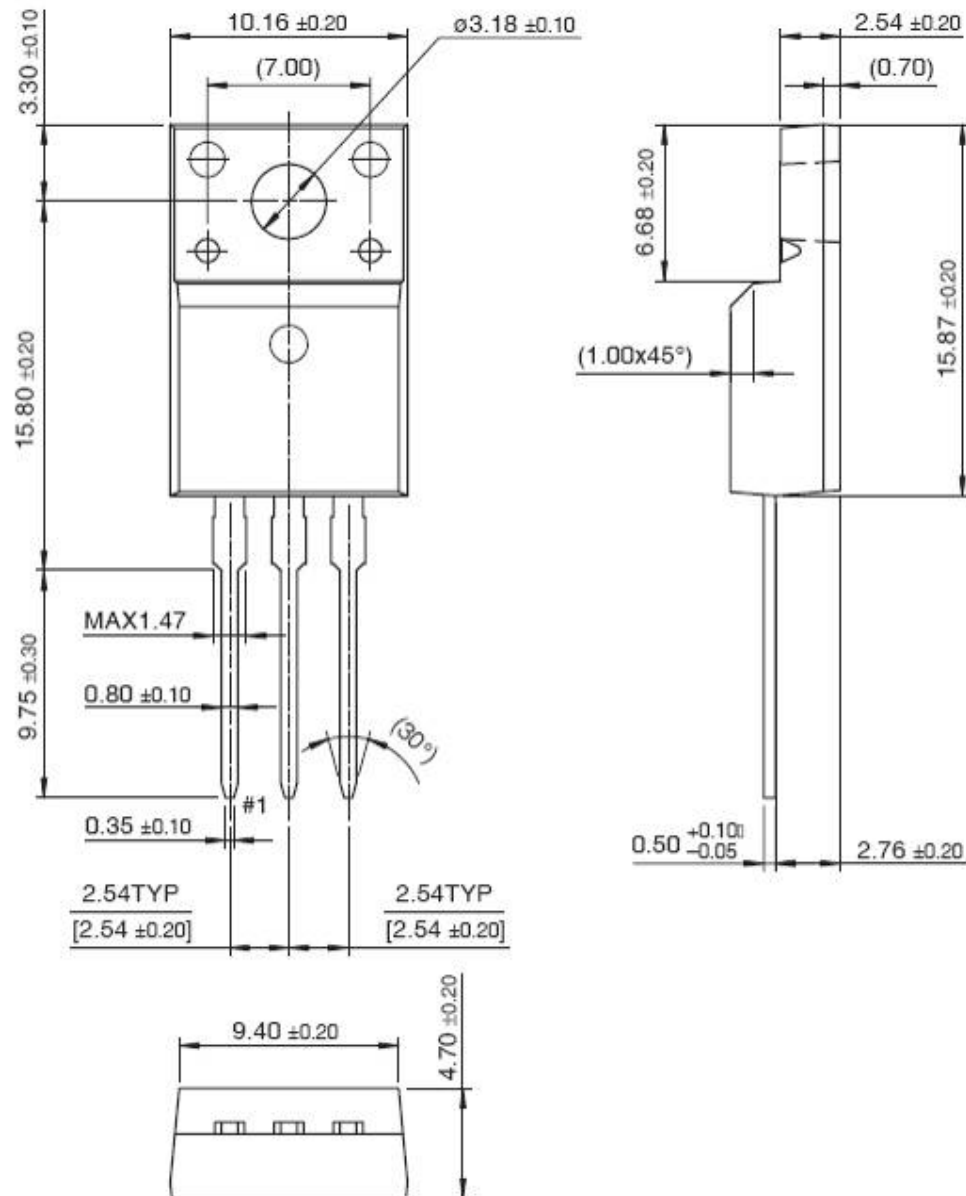


Figure 24. Unclamped Inductive Switching Waveforms

Package Dimensions
TO-220


TO-220F



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